



STC4301D 

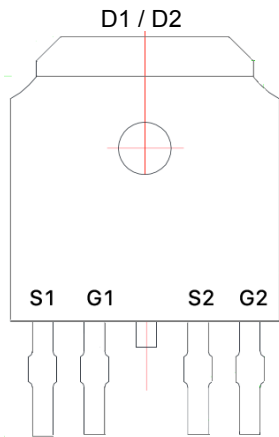
N&P Pair Enhancement Mode MOSFET

23.0A / -20.0A

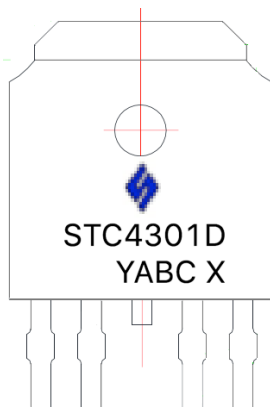
DESCRIPTION

The STC4301D is the N & P-Channel enhancement mode power field effect transistor using high cell density DMOS trench technology. This high density process is especially tailored to minimize on-state resistance and provide superior switching performance. This device is particularly suited for low voltage application such as power management, where high-side switching, low in-line power loss and resistance to transient are needed.

**PIN CONFIGURATION
TO252-4L**



PART MARKING



- Y : Year
- A : Date code
- B/C : Process Code
- X : Package Code

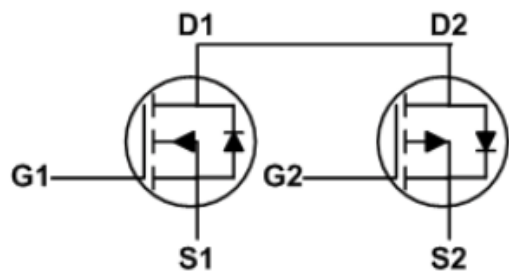
FEATURE

N-Channel

- 40V/12.0A, $R_{DS(ON)} = 25m\Omega$
@ $V_{GS} = 10V$
- 40V/10.0A, $R_{DS(ON)} = 32m\Omega$
@ $V_{GS} = 4.5V$

P-Channel

- -40V/-8.0A, $R_{DS(ON)} = 40m\Omega$
@ $V_{GS} = -10V$
- -40V/-4.0A, $R_{DS(ON)} = 65m\Omega$
@ $V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- TO252-4L package



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STC4301D



N&P Pair Enhancement Mode MOSFET

23.0A / -20.0A

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter		Symbol	Typical		Unit
			N	P	
Drain-Source Voltage		V _{DSS}	40	-40	V
Gate-Source Voltage		V _{GSS}	±20	±20	V
Continuous Drain Current	T _A =25°C	I _D	23.0	-20.0	A
	T _A =70°C		18.0	-16.0	
Pulsed Drain Current		I _{DM}	40	-46	A
Continuous Source Current (Diode Conduction)		I _S	18	-27.5	A
Power Dissipation	T _A =25°C	P _D	25	31.5	W
Operation Junction Temperature		T _J	150		°C
Storage Temperature Range		T _{STG}	-55/150		°C
Thermal Resistance-Junction to Ambient		R _{θJA}	62.5	62.5	°C/W



STC4301D



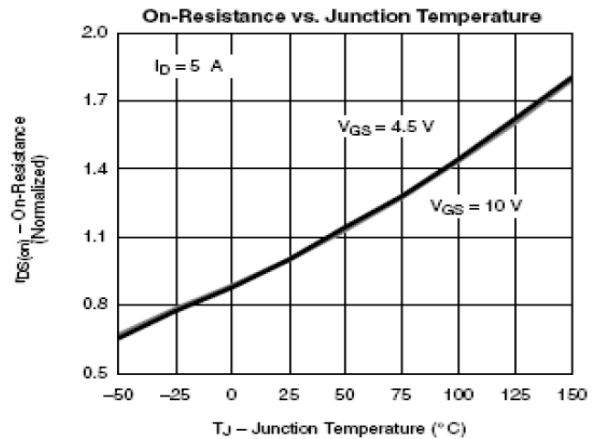
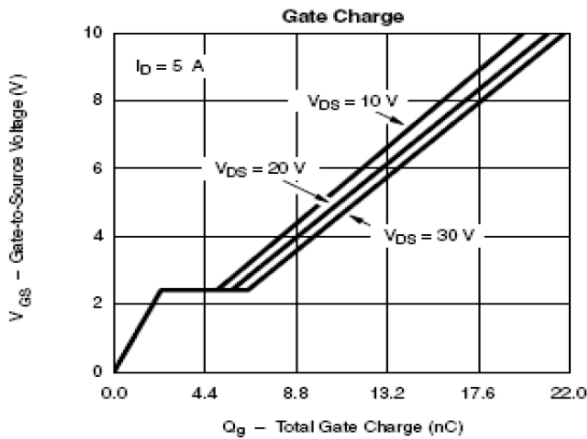
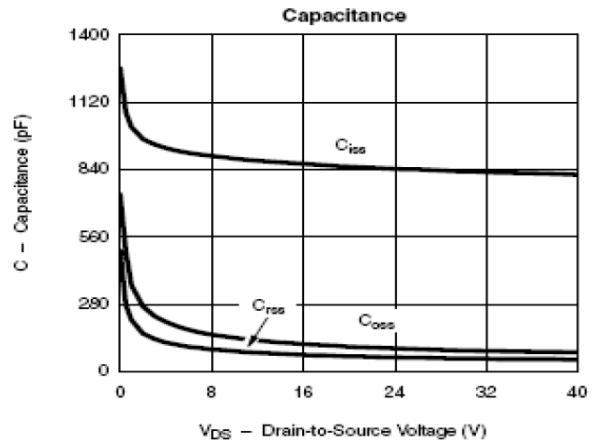
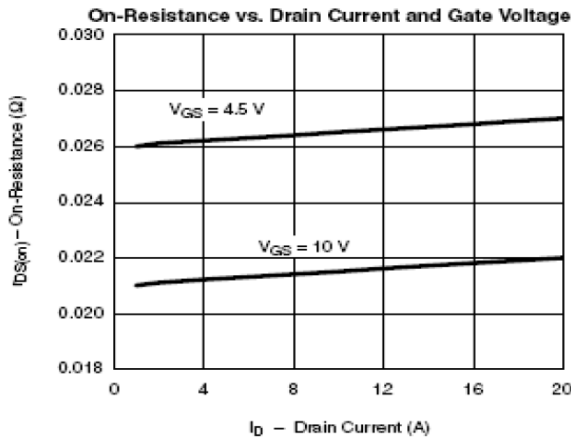
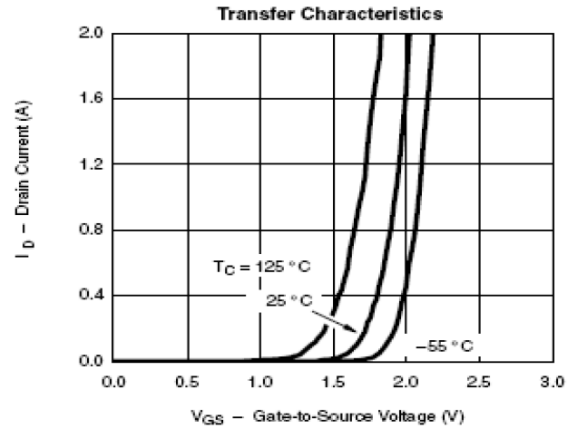
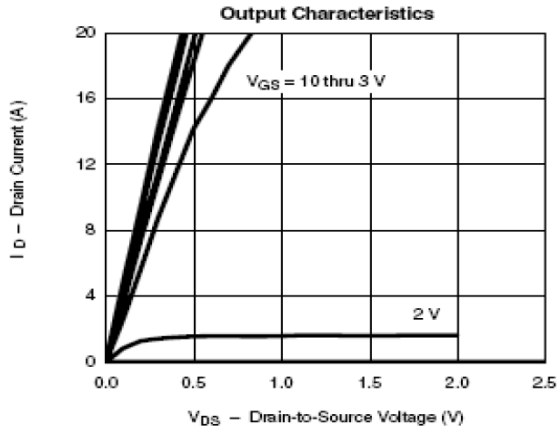
N&P Pair Enhancement Mode MOSFET

23.0A / -20.0A

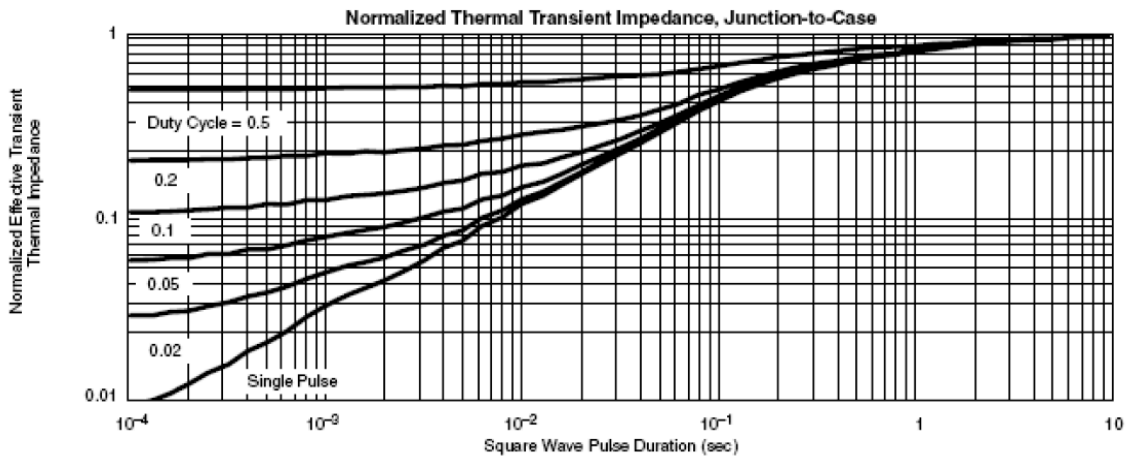
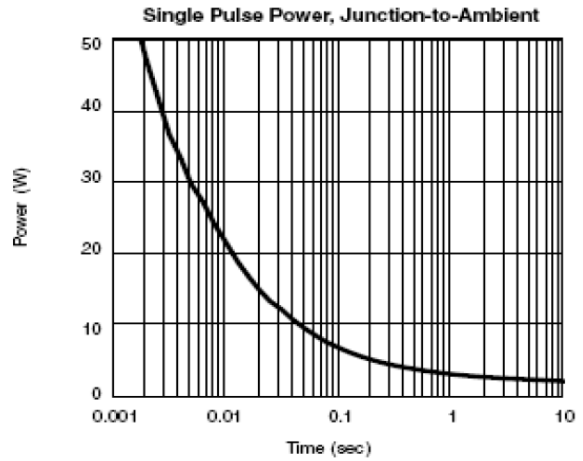
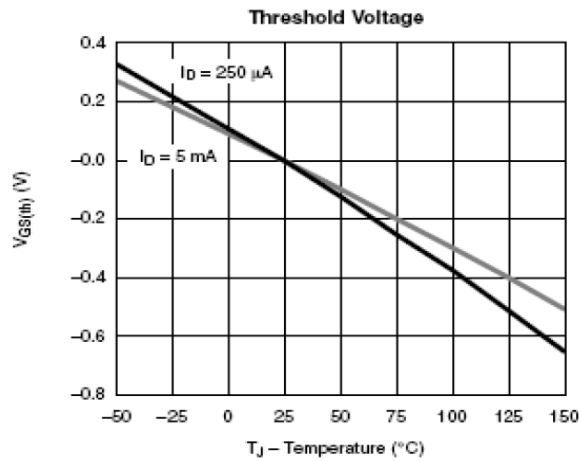
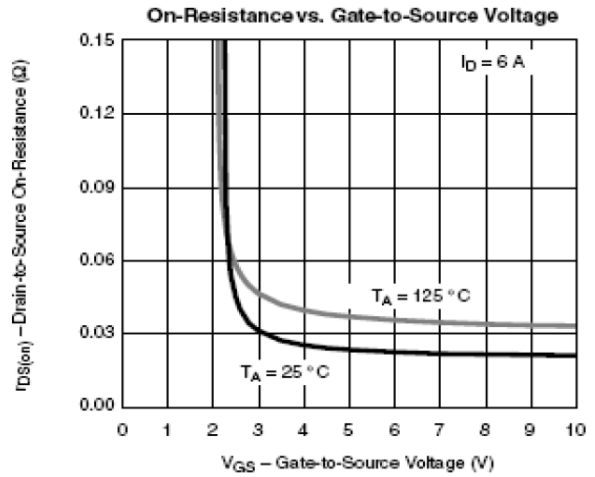
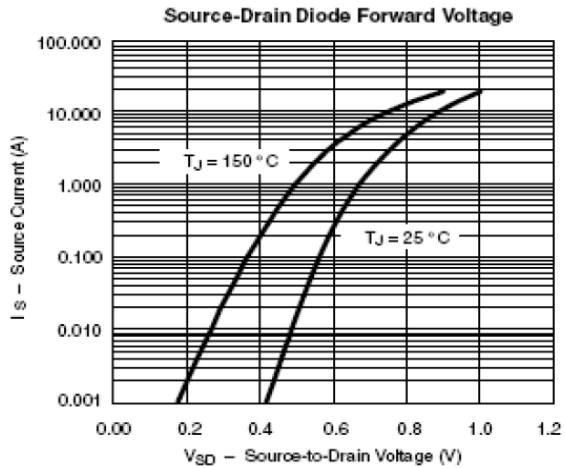
ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=10mA$ $V_{GS}=0V, I_D=-10mA$	N P	40 -40		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250 \mu A$ $V_{DS}=V_{GS}, I_D=-250\mu A$	N P	1.0 -1.0	2.5 -2.5	V
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$ $V_{DS}=0V, V_{GS}=\pm 20V$	N P		± 100 ± 100	nA
Zero Gate Voltage Drain Current	I_{DSS} $T_J=25^\circ C$ $T_J=55^\circ C$	$V_{DS}=32V, V_{GS}=0V$ $V_{DS}=-32V, V_{GS}=0V$	N P		1 -1	μA
		$V_{DS}=32V, V_{GS}=0V$ $V_{DS}=-32V, V_{GS}=0V$	N P		5 -5	
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10.0A$ $V_{GS}=-10V, I_D=-10.0A$	N P		0.025 0.035	Ω
		$V_{GS}=4.5V, I_D=6.0A$ $V_{GS}=-4.5V, I_D=-5.0 A$	N P		0.030 0.040	
					0.037 0.065	
Forward Tran Conductance	g_{fs}	$V_{DS}=5V, I_D=12.0A$ $V_{DS}=-5V, I_D=-8.0A$	N P		8 12.6	S
Diode Forward Voltage	V_{SD}	$I_S=1.0A, V_{GS}=0V$	N		1.2	V
		$I_S=-1.0A, V_{GS}=0V$	P		-1.2	
Dynamic						
Total Gate Charge	Q_g	N-Channel $V_{DS}=20V, V_{GS}=4.5V$ $I_D=12.0A$ P-Channel $V_{DS}=-20V, V_{GS}=-4.5V$ $I_D=-12.0A$	N		5.5	nC
Gate-Source Charge	Q_{gs}		P		9	
Gate-Drain Charge	Q_{gd}		N		1.25	
Turn-On Time	$t_{d(on)}$ t_r	N-Channel $V_{DS}=20V, R_G=3.3 \Omega$ $I_D=1A, V_{GS}=10V$	N		8.9	nS
			P		18.7	
			N		2.2	
			P		12.7	
Turn-Off Time	$t_{d(off)}$ t_f	P-Channel $V_{DS}=-20V, R_G=3.3 \Omega$ $I_D=-1A, R_{GS}=-10V$	N		15.6	
			P		30.2	
			N		3.0	
			P		15	

TYPICAL CHARACTERISTICS (N MOS)



TYPICAL CHARACTERISTICS (N MOS)



TYPICAL CHARACTERISTICS (P MOS)

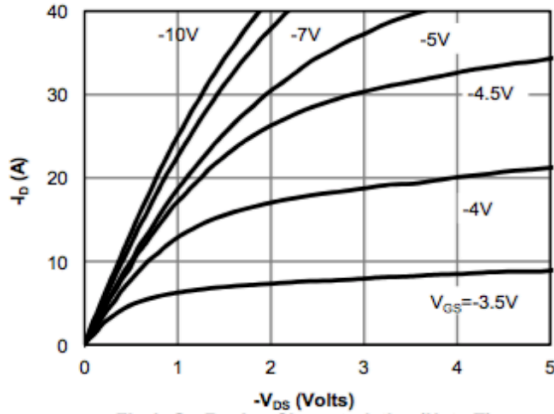


Figure 1: On-Region Characteristics (Note E)

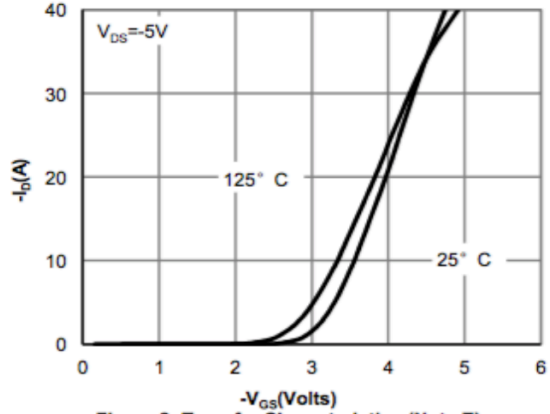


Figure 2: Transfer Characteristics (Note E)

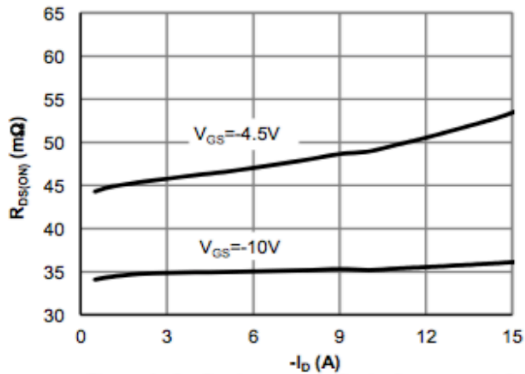


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

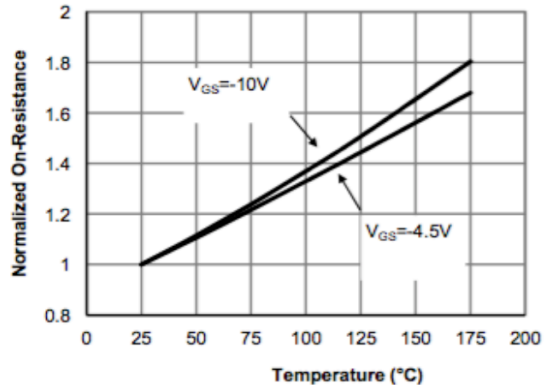


Figure 4: On-Resistance vs. Junction Temperature (Note E)

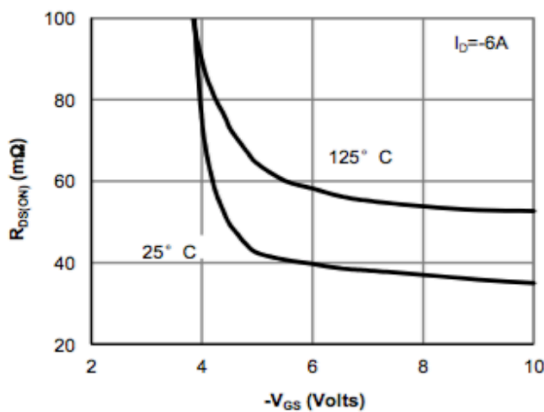


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

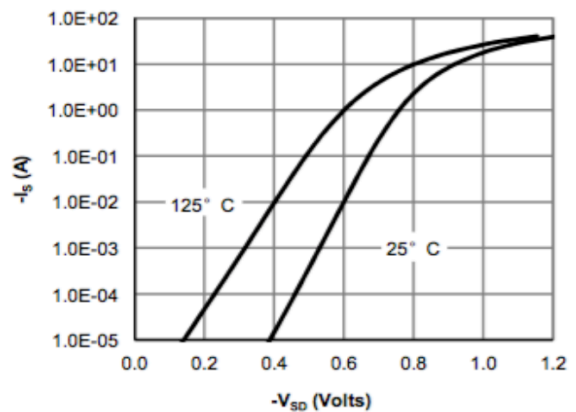


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL CHARACTERISTICS (P MOS)

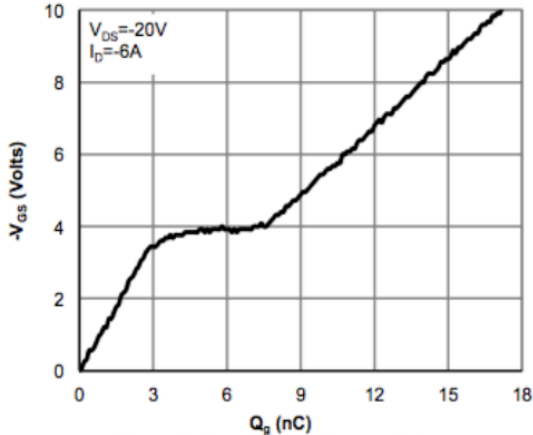


Figure 7: Gate-Charge Characteristics

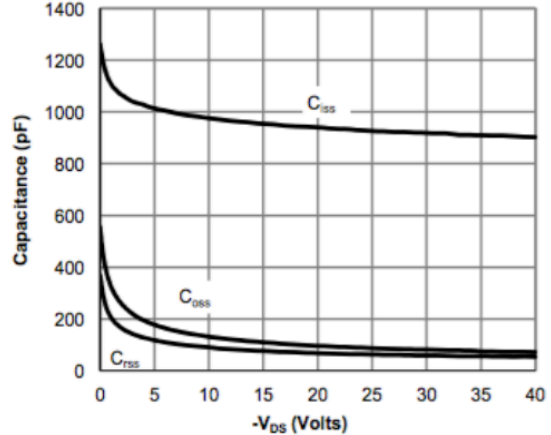


Figure 8: Capacitance Characteristics

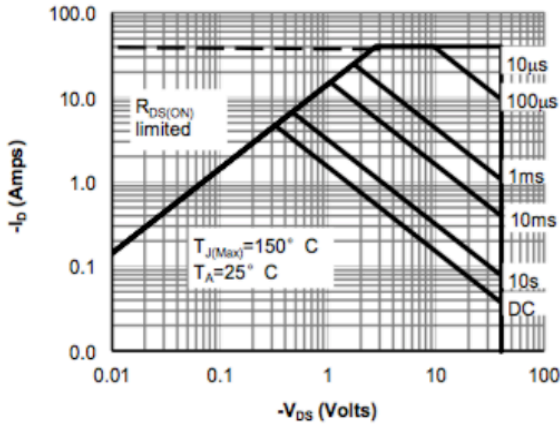


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

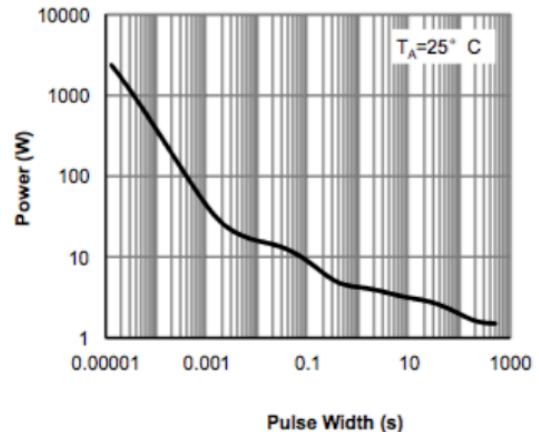


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

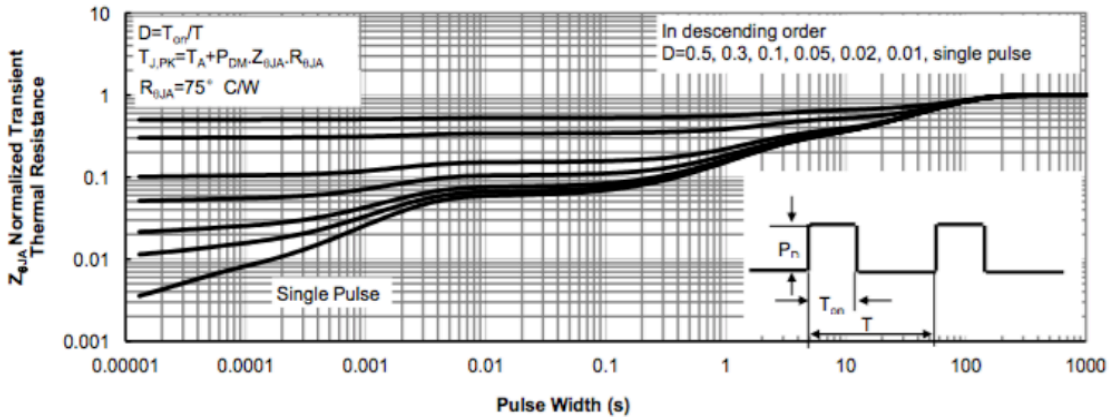


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

TO252-4L PACKAGE OUTLINE

